Cross-Section View VS1003B
49pin FBGA (RoHS) Package

Substrate
plate composition: Cu, Au and Ni
plate thickness: Cu = 18 microns
Au = 0.3-1.0 microns
Ni = 5.0 microns minimum
Total substrate thickness: 0.20 MM +/- 0.04 MM

Material
Solderball Sn 96.5%, Ag 3%, Cu 0.5%
Substrate HL832NX, AUS 308
Epoxy Die Attach ABLEBOND 2000B
Bonding Wire 25 um
Mold Compound EMEG760V